DF3A6.8FUT1

Preferred Device

Zener ESD Protection Diode

Dual Common Anode Zeners for ESD Protection

These dual monolithic silicon zener diodes are designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. Their dual junction common anode design protects two separate lines using only one package. These devices are ideal for situations where board space is at a premium.



- Pb-Free Package is Available
- SC-70 Package Allows Two Separate Unidirectional Configurations
- Low Leakage < 1.0 μA @ 5.0 V
- Breakdown Voltage: 6.4-7.2 V @ 5.0 mA
- ESD Protection Meeting:16 kV Human Body Model
 - 30 kV Contact = IEC61000-4-2
- Peak Power: 24 W @ 1.0 ms (Unidirectional), per Figure 1
- Peak Power: 150 W @ 20 \u03c4s (Unidirectional), per Figure 2

Mechanical Characteristics

- Void Free, Transfer-Molded, Thermosetting Plastic Case
- Corrosion Resistant Finish, Easily Solderable
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Steady State Power Dissipation Derate above 25°C (Note 1)	P _D	200 1.6	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	618	°C/W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	– 55 to +150	°C
Peak Power Dissipation @ 1.0 ms (Note 2) @ T _A = 25°C	P _{PK}	20	W
Peak Power Dissipation @ 20 μs (Note 3) @ T _A = 25°C	P _{PK}	150	W
ESD Discharge MIL STD 883C - Method 3015-6 IEC61000-4-2, Air Discharge IEC61000-4-2, Contact Discharge	V _{PP}	16 30 30	kV

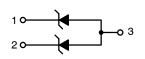
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Mounted on FR-5 Board = 1.0 X 0.75 X 0.062 in.
- 2. Non-repetitive pulse per Figure 1.
- 3. Non-repetitive pulse per Figure 2.

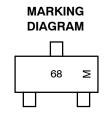


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68 = Specific Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
DF3A6.8FUT1	SC-70	3000/Tape & Reel
DF3A6.8FUT1G	SC-70 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

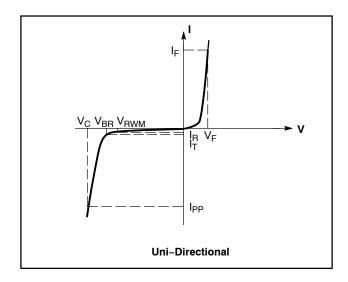
DF3A6.8FUT1

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ V _{RWM}
V_{BR}	Breakdown Voltage @ I _T
I _T	Test Current
I _F	Forward Current
V _F	Forward Voltage @ I _F
Z _{ZT}	Maximum Zener Impedance @ I _{ZT}
Z _{ZK}	Maximum Zener Impedance @ I _{ZK}



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward Voltage	V _F	I _F = 10 mA		0.8	0.9	V
Zener Voltage (Note 4)	VZ	I _{ZT} = 5 mA	6.4	6.8	7.2	V
Operating Resistance (Note 5)	Z _{ZK}	I _{ZK} = 0.5 mA			200	Ω
	Z _{ZT}	I _{ZT} = 5 mA			50	Ω
Reverse Current	I _{R1}	V _{RWM} = 5 V			0.5	μΑ
Clamping Voltage	V _C	I _{PP} = 2.0 A (Figure 1) I _{PP} = 9.37 A (Figure 2)			9.6	٧
					16	V
ESD Protection Human Body Model (HBM) Contact – IEC61000–4–2 Air Discharge					16 30 30	kV

 ^{4.} V_Z measured at pulse test current I_{ZT} at an ambient temperature of 25°C.
 5. Z_{ZT} and Z_{ZK} is measured by dividing the AC voltage drop across the device by the AC current supplied. AC frequency = 1.0 kHz.

DF3A6.8FUT1

TYPICAL CHARACTERISTICS

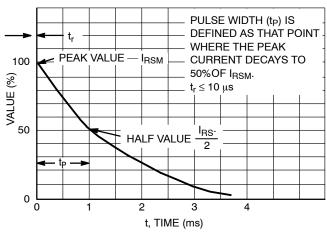


Figure 1. $10 \times 1000 \mu s$ Pulse Waveform

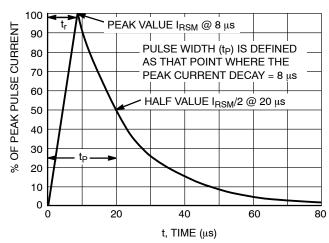


Figure 2. $8 \times 20 \mu s$ Pulse Waveform

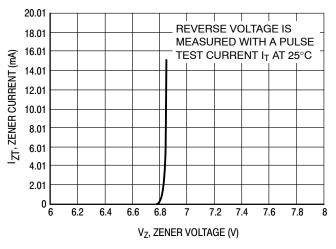


Figure 3. Zener Voltage vs. Zener Current

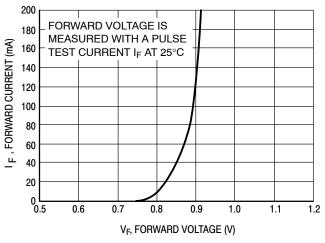


Figure 4. Forward Voltage vs. Forward Current

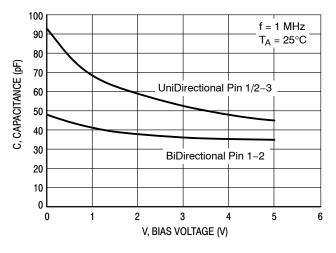


Figure 5. Capacitance vs. Bias Voltage

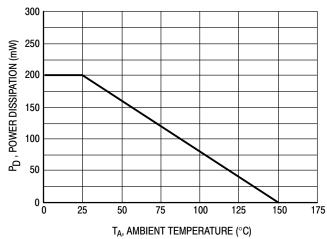
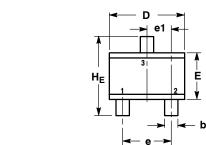


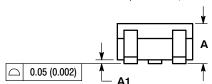
Figure 6. Steady State Power Derating Curve

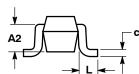


SC-70 (SOT-323) CASE 419-04 ISSUE N

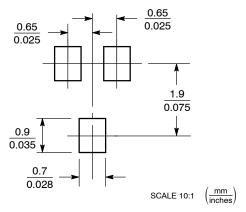
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SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC				0.026 BSC	;
Ĺ	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095

GENERIC MARKING DIAGRAM



XX = Specific Device Code

Μ = Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1: CANCELLED	STYLE 2: PIN 1. ANODE 2. N.C. 3. CATHODE	STYLE 3: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. CATHODE	
STYLE 6:	STYLE 7:	STYLE 8:	STYLE 9:	STYLE 10:	STYLE 11:
PIN 1. EMITTER	PIN 1. BASE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. CATHODE
2. BASE	2. EMITTER	2. SOURCE	2. CATHODE	2. ANODE	CATHODE
COLLECTOR	COLLECTOR	3. DRAIN	CATHODE-ANODE	3. ANODE-CATHODE	CATHODE

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DESCRIPTION:	SC-70 (SOT-323)		PAGE 1 OF 1	

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